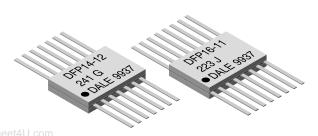
Vishay Dale



Thick Film Resistor Networks Flat Pack, 11, 12 Schematics

FEATURES

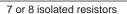
- 11 and 12 Schematics
- 0.065" [1.65mm] height for high density packaging
- Low temperature coefficient (- 55°C to + 125°C) ± 100ppm/°C
- Hot solder dipped leads
- Highly stable thick film
- Wide resistance range
- All devices are capable of passing the MIL-STD-202, Method 210, Condition C "Resistance to Soldering Heat" test



STANDARD ELECTRICAL SPECIFICATIONS									
	POWER RATING			LIMITING ELEMENT	TEMPERATURE ¹⁾	STANDARD ²⁾	RESISTANCE	TEMPERATURE	
GLOBAL MODEL	P _{25°C} ELEMENT W	P _{25°C} PACKAGE W	CIRCUIT SCHEMATIC	VOLTAGE MAX. V≌	COEFFICIENT ppm/°C	TOLERANCE %	RANGE Ω	COEFFICIENT TRACKING ppm/°C	
DFP	0.25	0.65	11	75	± 100	2	10 - 1M	50	
DIFF	0.15	0.65	12	75	± 100	2	10 - 1M	50	

¹⁾Temperature Range: - 55°C to + 125°C 2) ± 1% and ± 5% tolerance available

TECHNICAL SPECIFICATIONS



The DFPxx11 provides the user with 7 or 8 nominally equal resistors with each resistor isolated from all others. Commonly used in the following applications:

- "Wired OR" Pull-up
- Power Driven Pull-up
- Power Gate Pull-up
- Line Termination
- Long-line Impedance Balancing
- LED Current Limiting
- ECL Output Pull-down
- TTL Input Pull-down



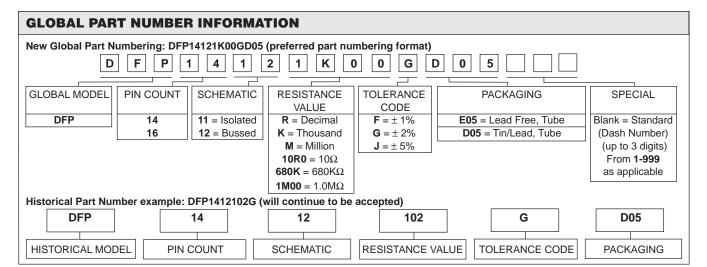
11 Schematic



13 or 15 resistors with one pin common

The DFPxx12 provides the user with a choice of 13 or 15 nominally equal resistors, each connected to a common pin (14 or 16). Commonly used in the following applications:

- MOS/ROM Pull-up/Pull-down
- Open Collector Pull-up
- "Wired OR" Pull-upPower Driven Pull-up
- TTL Input Pull-down
- Digital Pulse Squaring
- TTL Unused Gate Pull-up
- High Speed Parallel Pull-up



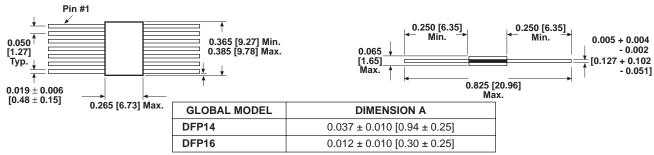
Consult factory for stocked values





Thick Film Resistor, Networks, Flat Pack

DIMENSIONS in inches [millimeters]



www.DataSheet4II.com

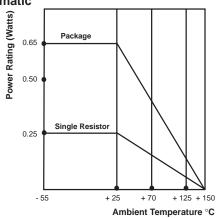
TECHNICAL SPECIFICATIONS						
PARAMETER	UNIT	DFP14 / 16				
Isolation Resistance 11 Schematic	MΩ	> 100				
Voltage Coefficient of Resistance:	ppm/V	< 50 typical				
Maximum Operating Voltage:	VDC	75				
Operating Temperature Range:	°C	- 55 to + 125				
Storage Temperature Range:	°C	- 55 to + 150				

MECHANICAL SPECIFICATIONS					
Marking:	Model number, schematic number, value tolerance, pin 1 indicator, date code.				
Marking Resistance to Solvents:	Permanency testing per MIL-STD-202 Method 215.				
Solderability:	Per MIL-STD-202, Method 208E.				
Terminals:	Per MIL-STD-1276 DFPxx11, DFPxx12 = Type G (hot solder dipped). Hot solder dipped leads supplied as standard finish.				
Body:	Epoxy filled ceramic sandwich				

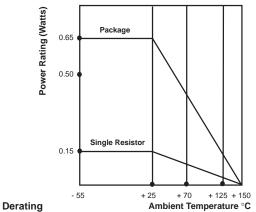
11 Schematic

Derating

PERFORMANCE



12 Schematic



TEST	CONDITIONS	MAX. ∆R (Typical Test Lots)	
Power Conditioning	1.5 x rated power, applied 1.5 hours "ON" and 0.5 hour "OFF" for 100 hours ± 4 hours at + 25°C ambient temperature	± 0.50% ∆R	
Thermal Shock	5 cycles between - 65°C and + 125°C	± 0.50% ΔR	
Short Time Overload	2.5 x rated working voltage, 5 seconds	± 0.25% ΔR	
Low Temperature Operation	45 minutes at full rated working voltage at - 65°C	± 0.25% ΔR	
Moisture Resistance	240 hours with humidity ranging from 80% RH to 98% RH	± 0.50% ΔR	
Resistance to Soldering Heat	Leads immersed in + 260°∆C solder to within 1/16" of body for 10 seconds	± 0.25% ΔR	
Shock	Total of 18 shocks at 100 G's	± 0.25% ΔR	
Vibration	12 hours at maximum of 20 G's between 10 and 2,000 Hz	± 0.25% ΔR	
Load Life	1000 hours at + 70°C, rated power applied 1.5 hours "ON", 0.5 hour "OFF" for full 1000 hour period. Derated according to the curve.	± 0.50% ΔR	

Document Number: 31513 Revision: 08-Sep-04

Terminal Strength

Insulation Resistance

Dielectric Withstanding Voltage

No evidence of arcing or damage (200 V RMS for 1 minute)

1.5 pound pull for 30 seconds

10,000 Megohm (minimum)

± 0.25% ΔR